熱可塑系樹脂(エンプラ/スーパーエンプラ)への 密着に優れた

Excellent adhesion to thermoplastic resins (engineering plastics / super engineering plastics)

立体成型基板用ソルダーレジスト

S-500MD Series Solder resist for MID

3D-MID 作製方法

Process flow of 3D-MID





Molding

Patterning Copper plating

Resist coating

Leaser trimming E' less Ni/Au Plating

SMT

ソルダーレジストの役割 Roles of Solder resist

① 実装時のはんだ流れ防止 Prevention of solder outflow



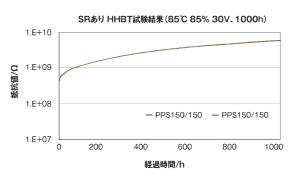
150°C





② 高絶縁信頼性

High insulation reliability



製品ラインナップ S-500 MD Series

LCP · PPS · PEEK

PBT · PA4T PA6/6T · PA6T/X PA10/T · PA1010

PC · PPE · ABS PC/ABS

[S-500 MD300] LCP用 PPS·PEEK用 「S-500 MD300」

PA, PBT用 [S-50 MD200]

ABS/PC用 [S-500 MD100]